



Program

14:00	Welcome coffee and registration
14:30	Welcome message, HTA presentation Laurent HERAULT , CEA-Leti, HTA Chair 2018
14:45	Future of micro- and nanosystems in H2020 and FP9 Lucilla SIOLI , European Commission DG CONNECT Director
15:00	European solutions for the global market Hubert LAKNER , chair Fraunhofer Microelectronics Group
15:15	European cooperation in the context of the IPCEI Gerd TEEPE , VP GlobalFoundries
15:30	Swiss microtechnologies in the European innovation ecosystem Mario EL-KHOURY , CEO CSEM
15:45	Smart technology use in packaging and the benefits for the food industry Robert WITIK , Senior Specialist, Sustainability & Packaging Material Science, Nestlé Research Center
16:00	Break
16:15	From vision to growth: role of research in building world-class excellence in future added value electronics Antti VASARA , CEO VTT
16:30	Global view on European R&D collaboration Anssi KORHONEN , VP Murata Electronics Oy
16:45	European low-power, smart and secure technologies in the age of hyperconnectivity Emmanuel SABONNADIERE , CEO CEA-Leti
17:00	European innovation from substrates to devices integration José BERIOT , VP SOITEC
17.15	Demonstrators / Pitches
17.45	Outlook & Closing Remarks Laurent HERAULT , CEA-Leti
18.00	Reception & Networking